



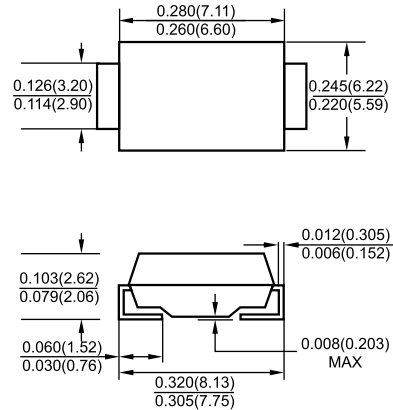
SMC/DO-214AB

Features

- ✧ Glass passivated junction chip
- ✧ For surface mounted applications
- ✧ Low profile package
- ✧ Built-in strain relief
- ✧ Ideal for automated placement
- ✧ Easy pick and place
- ✧ Super fast recovery time for high efficiency
- ✧ Glass passivated chip junction
- ✧ High temperature soldering:
260°C/10 seconds at terminals
- ✧ Plastic material used carries Underwriters
Laboratory Classification 94V-0

Mechanical Data

- ✧ Cases: Molded plastic
- ✧ Terminals: Pure tin plated, lead free.
- ✧ Polarity: Indicated by cathode band
- ✧ Weight: 0.21 gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	ES 3A	ES 3B	ES 3C	ES 3D	ES 3F	ES 3G	ES 3H	ES 3J	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS Voltage	V _{RMS}	35	70	105	140	210	280	350	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	500	600	V
Maximum Average Forward Rectified Current See Fig. 1	I _(AV)	3.0								A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) @T _L = 100 °C	I _{FSM}	100								A
Maximum Instantaneous Forward Voltage @ 3.0A	V _F	0.95				1.3		1.7		V
Maximum DC Reverse Current @ T _A =25 °C at Rated DC Blocking Voltage @ T _A =100 °C	I _R	10 500								uA uA
Maximum Reverse Recovery Time (Note 1)	T _{rr}	35								nS
Typical Junction Capacitance (Note 2)	C _j	45				30				pF
Typical Thermal Resistance (Note 3)	R _{θJA} R _{θJL}	47 12								°C /W
Operating Temperature Range	T _J	-55 to +150								°C
Storage Temperature Range	T _{STG}	-55 to +150								°C

- Notes:
1. Reverse Recovery Test Conditions: $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{RR} = 0.25\text{A}$
 2. Measured at 1 MHz and Applied $V_R = 4.0\text{ Volts}$
 3. Units Mounted on P.C.B. with 0.6" x 0.6" (16mm x 16mm) Copper Pad Areas

RATINGS AND CHARACTERISTIC CURVES (ES3A THRU ES3J)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

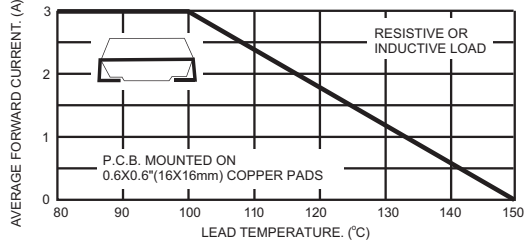


FIG.2- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

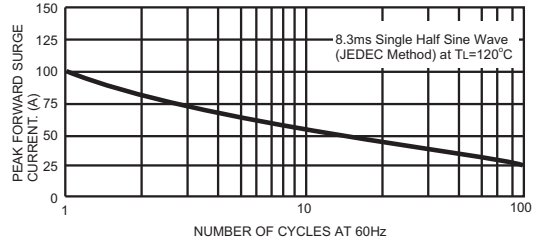


FIG.3- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

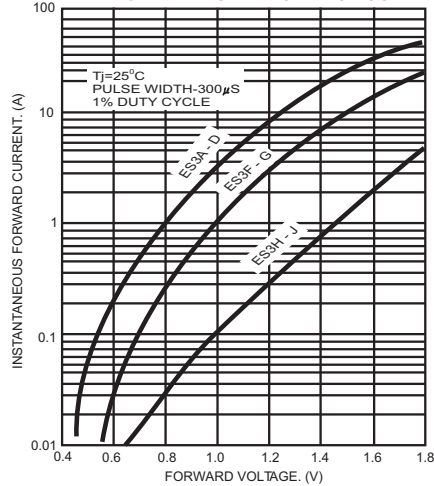


FIG.4- TYPICAL REVERSE CHARACTERISTICS

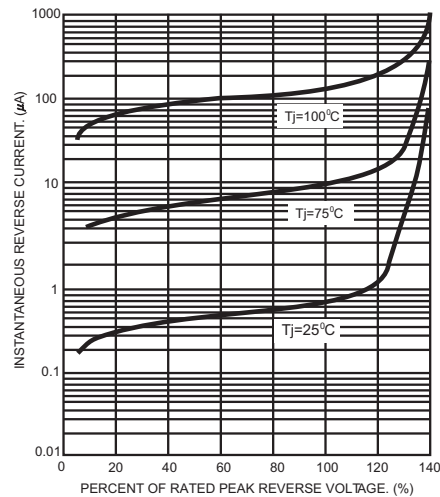


FIG.5- TYPICAL JUNCTION CAPACITANCE

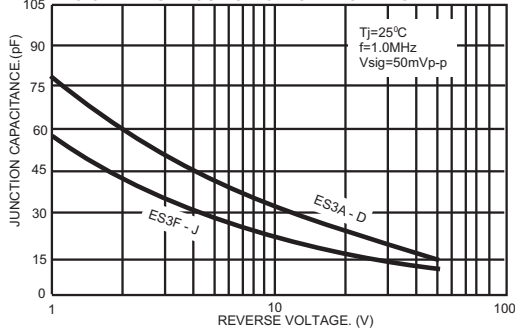


FIG.6- TYPICAL TRANSIENT THERMAL IMPEDANCE

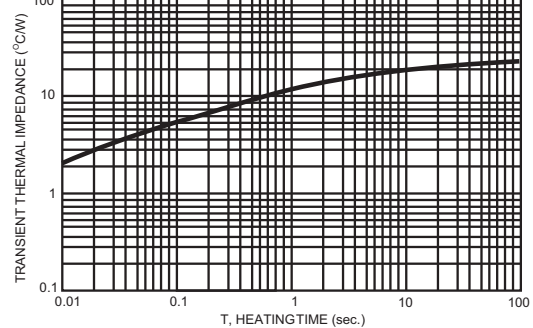


FIG.7- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

